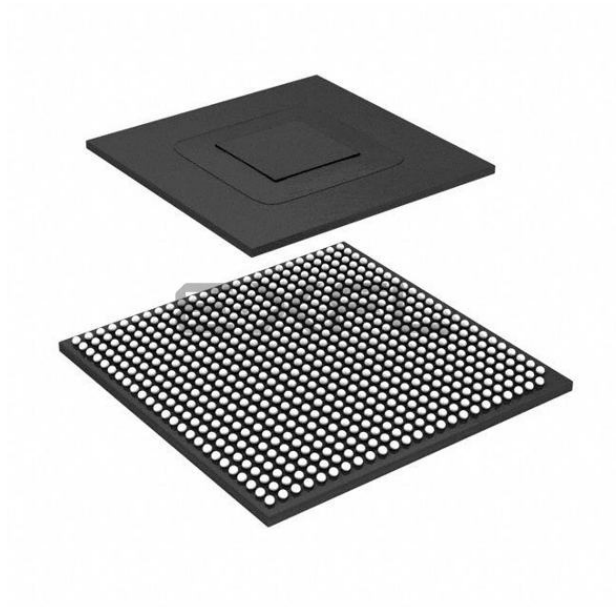

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

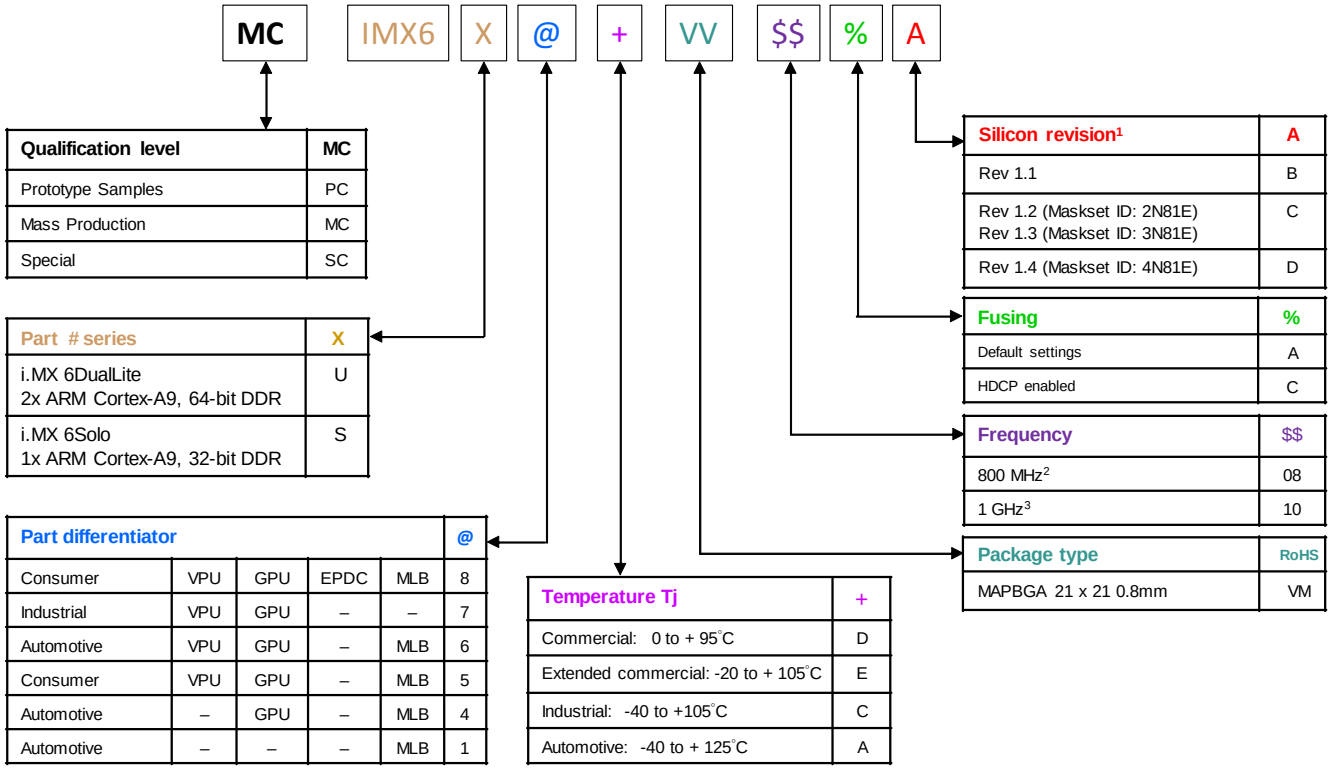
Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	ARM® Cortex®-A9
Number of Cores/Bus Width	2 Core, 32-Bit
Speed	1GHz
Co-Processors/DSP	Multimedia; NEON™ SIMD
RAM Controllers	LPDDR2, LVDDR3, DDR3
Graphics Acceleration	Yes
Display & Interface Controllers	Keypad, LCD
Ethernet	10/100/1000Mbps (1)
SATA	-
USB	USB 2.0 + PHY (4)
Voltage - I/O	1.8V, 2.5V, 2.8V, 3.3V
Operating Temperature	-40°C ~ 125°C (TJ)
Security Features	ARM TZ, Boot Security, Cryptography, RTIC, Secure Fusebox, Secure JTAG, Secure Memory, Secure RTC, Tamper Detection
Package / Case	624-LFBGA
Supplier Device Package	624-MAPBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcimx6u4avm10ac

- The *i.MX 6Solo/6DualLite Applications Processors for Industrial Products* data sheet (IMX6SDLIEC) covers parts listed with “C (Industrial temp)”

For more information go to nxp.com/imx6series or contact a NXP representative for details.



1. See the nxp.com\imx6series Web page for latest information on the available silicon revision.
2. If a 24 MHz input clock is used (required for USB), the maximum SoC speed is limited to 792 MHz.
3. If a 24 MHz input clock is used (required for USB), the maximum SoC speed is limited to 996 MHz.

Figure 1. Part Number Nomenclature—i.MX 6Solo and 6DualLite

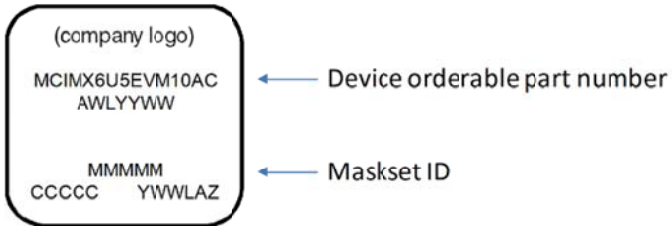


Figure 2. Example Part Marking

1.2 Features

The i.MX 6Solo/6DualLite processors are based on ARM Cortex-A9 MPCore Platform, which has the following features:

- The i.MX 6Solo supports single ARM Cortex-A9 MPCore (with TrustZone)
- The i.MX 6DualLite supports dual ARM Cortex-A9 MPCore (with TrustZone)
- The core configuration is symmetric, where each core includes:

  - LVDS serial ports—One port up to 165 Mpixels/sec or two ports up to 85 MP/sec (for example, WUXGA at 60 Hz) each
  - HDMI 1.4 port
  - MIPI/DSI, two lanes at 1 Gbps
- Camera sensors:
  - Two parallel Camera ports (up to 20 bit and up to 240 MHz peak)
  - MIPI CSI-2 Serial port, supporting from 80 Mbps to 1 Gbps speed per data lane. The CSI-2 Receiver core can manage one clock lane and up to two data lanes. Each i.MX 6Solo/6DualLite processor has two lanes.
- Expansion cards:
  - Four MMC/SD/SDIO card ports all supporting:
    - 1-bit or 4-bit transfer mode specifications for SD and SDIO cards up to UHS-I SDR-104 mode (104 MB/s max)
    - 1-bit, 4-bit, or 8-bit transfer mode specifications for MMC cards up to 52 MHz in both SDR and DDR modes (104 MB/s max)
- USB:
  - One high speed (HS) USB 2.0 OTG (Up to 480 Mbps), with integrated HS USB Phy
  - Three USB 2.0 (480 Mbps) hosts:
    - One HS host with integrated High Speed Phy
    - Two HS hosts with integrated HS-IC USB (High Speed Inter-Chip USB) Phy
- Expansion PCI Express port (PCIe) v2.0 one lane
  - PCI Express (Gen 2.0) dual mode complex, supporting Root complex operations and Endpoint operations. Uses x1 PHY configuration.
- Miscellaneous IPs and interfaces:
  - SSI block is capable of supporting audio sample frequencies up to 192 kHz stereo inputs and outputs with I^2S mode
  - ESAI is capable of supporting audio sample frequencies up to 260 kHz in I^2S mode with 7.1 multi channel outputs
  - Five UARTs, up to 5.0 Mbps each:
    - Providing RS232 interface
    - Supporting 9-bit RS485 multidrop mode
    - One of the five UARTs (UART1) supports 8-wire while others four supports 4-wire. This is due to the SoC IOMUX limitation, since all UART IPs are identical.
  - Four eCSPI (Enhanced CSPI)
  - Four I^2C, supporting 400 kbps
  - Gigabit Ethernet Controller (IEEE1588 compliant), 10/100/1000[1] Mbps
  - Four Pulse Width Modulators (PWM)

1. The theoretical maximum performance of 1 Gbps ENET is limited to 470 Mbps (total for Tx and Rx) due to internal bus throughput limitations. The actual measured performance in optimized environment is up to 400 Mbps. For details, see the ERR004512 erratum in the i.MX 6Solo/6DualLite errata document (IMX6SDLCE).

NOTE

The actual feature set depends on the part numbers as described in Table 1, "Example Orderable Part Numbers," on page 3. Functions, such as video hardware acceleration, and 2D and 3D hardware graphics acceleration may not be enabled for specific part numbers.

1.3 Updated Signal Naming Convention

The signal names of the i.MX6 series of products have been standardized to better align the signal names within the family and across the documentation. Some of the benefits of these changes are as follows:

- The names are unique within the scope of an SoC and within the series of products
- Searches will return all occurrences of the named signal
- The names are consistent between i.MX 6 series products implementing the same modules
- The module instance is incorporated into the signal name

This change applies only to signal names. The original ball names have been preserved to prevent the need to change schematics, BSDL models, IBIS models, etc.

Throughout this document, the updated signal names are used except where referenced as a ball name (such as the Functional Contact Assignments table, Ball Map table, and so on). A master list of the signal name changes is in the document, *IMX 6 Series Signal Name Mapping* (EB792). This list can be used to map the signal names used in older documentation to the new standardized naming conventions.

3 Modules List

The i.MX 6Solo/6DualLite processors contain a variety of digital and analog modules. Table 2 describes these modules in alphabetical order.

Table 2. i.MX 6Solo/6DualLite Modules List

Block Mnemonic	Block Name	Subsystem	Brief Description
APBH-DMA	NAND Flash and BCH ECC DMA controller	System Control Peripherals	DMA controller used for GPMI2 operation
ARM	ARM Platform	ARM	The ARM Core Platform includes 1x (Solo) Cortex-A9 core for i.MX 6Solo and 2x (Dual) Cortex-A9 cores for i.MX 6DualLite. It also includes associated sub-blocks, such as the Level 2 Cache Controller, SCU (Snoop Control Unit), GIC (General Interrupt Controller), private timers, watchdog, and CoreSight debug modules.
ASRC	Asynchronous Sample Rate Converter	Multimedia Peripherals	The Asynchronous Sample Rate Converter (ASRC) converts the sampling rate of a signal associated to an input clock into a signal associated to a different output clock. The ASRC supports concurrent sample rate conversion of up to 10 channels of about -120dB THD+N. The sample rate conversion of each channel is associated to a pair of incoming and outgoing sampling rates. The ASRC supports up to three sampling rate pairs.
AUDMUX	Digital Audio Mux	Multimedia Peripherals	The AUDMUX is a programmable interconnect for voice, audio, and synchronous data routing between host serial interfaces (for example, SSI1, SSI2, and SSI3) and peripheral serial interfaces (audio and voice codecs). The AUDMUX has seven ports with identical functionality and programming models. A desired connectivity is achieved by configuring two or more AUDMUX ports.
BCH40	Binary-BCH ECC Processor	System Control Peripherals	The BCH40 module provides up to 40-bit ECC for NAND Flash controller (GPMI)
CAAM	Cryptographic accelerator and assurance module	Security	CAAM is a cryptographic accelerator and assurance module. CAAM implements several encryption and hashing functions, a run-time integrity checker, and a Pseudo Random Number Generator (PRNG). The pseudo random number generator is certified by Cryptographic Algorithm Validation Program (CAVP) of National Institute of Standards and Technology (NIST). Its DRBG validation number is 94 and its SHS validation number is 1455. CAAM also implements a Secure Memory mechanism. In i.MX 6Solo/6DualLite processors, the security memory provided is 16 KB.
CCM GPC SRC	Clock Control Module, General Power Controller, System Reset Controller	Clocks, Resets, and Power Control	These modules are responsible for clock and reset distribution in the system, and also for the system power management.
CSI	MIPI CSI-2 i/f	Multimedia Peripherals	The CSI IP provides MIPI CSI-2 standard camera interface port. The CSI-2 interface supports from 80 Mbps to 1 Gbps speed per data lane.

4.1.5 Maximum Supply Currents

The Power Virus numbers shown in Table 10 represent a use case designed specifically to show the maximum current consumption possible. All cores are running at the defined maximum frequency and are limited to L1 cache accesses only to ensure no pipeline stalls. Although a valid condition, it would have a very limited practical use case, if at all, and be limited to an extremely low duty cycle unless the intention was to specifically show the worst case power consumption.

The NXP power management IC, MMPF0100xxxx, which is targeted for the i.MX 6 series processor family, supports the power consumption shown in Table 10, however a robust thermal design is required for the increased system power dissipation.

See the i.MX 6Solo/6DualLite Power Consumption Measurement Application Note (AN4576) for more details on typical power consumption under various use case definitions.

Table 10. Maximum Supply Currents

Power Line	Conditions	Max Current	Unit
VDD_ARM_IN	i.MX 6DualLite: 996 MHz ARM clock based on Power Virus operation	2200	mA
	i.MX 6Solo: 996 MHz ARM clock based on Power Virus operation	1320	mA
VDD_SOC_IN	996 MHz ARM clock	1260	mA
VDD_HIGH_IN	—	125[1]	mA
VDD_SNVS_IN	—	275[2]	µA
USB_OTG_VBUS/ USB_H1_VBUS (LDO 3P0)	—	25[3]	mA
Primary Interface (IO) Supplies			
NVCC_DRAM	—	—[4]	—
NVCC_ENET	N=10	Use maximum IO equation[5]	—
NVCC_LCD	N=29	Use maximum IO equation[5]	—
NVCC_GPIO	N=24	Use maximum IO equation[5]	—
NVCC_CSI	N=20	Use maximum IO equation[5]	—
NVCC_EIM	N=53	Use maximum IO equation[5]	—
NVCC_JTAG	N=6	Use maximum IO equation[5]	—
NVCC_RGMII	N=6	Use maximum IO equation[5]	—
NVCC_SD1	N=6	Use maximum IO equation[5]	—
NVCC_SD2	N=6	Use maximum IO equation[5]	—
NVCC_SD3	N=11	Use maximum IO equation[5]	—
NVCC_NANDF	N=26	Use maximum IO equation[5]	—

4.1.7 USB PHY Current Consumption

4.1.7.1 Power Down Mode

In power down mode, everything is powered down, including the USB_VBUS valid detectors in typical condition. Table 12 shows the USB interface current consumption in power down mode.

Table 12. USB PHY Current Consumption in Power Down Mode

	VDD_USB_CAP (3.0 V)	VDD_HIGH_CAP (2.5 V)	NVCC_PLL_OUT (1.1 V)
Current	5.1 µA	1.7 µA	<0.5 µA

NOTE

The currents on the VDD_HIGH_CAP and VDD_USB_CAP were identified to be the voltage divider circuits in the USB-specific level shifters.

4.1.8 PCIe 2.0 Power Consumption

Table 13 provides PCIe PHY currents under certain Tx operating modes.

Table 13. PCIe PHY Current Drain

Mode	Test Conditions	Supply	Max Current	Unit
P0: Normal Operation	5G Operations	PCIE_VP (1.1 V)	40	mA
		PCIE_VPTX (1.1 V)	20	
		PCIE_VPH (2.5 V)	21	
	2.5G Operations	PCIE_VP (1.1 V)	27	
		PCIE_VPTX (1.1 V)	20	
		PCIE_VPH (2.5 V)	20	
P0s: Low Recovery Time Latency, Power Saving State	5G Operations	PCIE_VP (1.1 V)	30	mA
		PCIE_VPTX (1.1 V)	2.4	
		PCIE_VPH (2.5 V)	18	
	2.5G Operations	PCIE_VP (1.1 V)	20	
		PCIE_VPTX (1.1 V)	2.4	
		PCIE_VPH (2.5 V)	18	
P1: Longer Recovery Time Latency, Lower Power State	—	PCIE_VP (1.1 V)	12	mA
		PCIE_VPTX (1.1 V)	2.4	
		PCIE_VPH (2.5 V)	12	

Table 13. PCIe PHY Current Drain (continued)

Mode	Test Conditions	Supply	Max Current	Unit
Power Down	—	PCIE_VP (1.1 V)	1.3	mA
		PCIE_VPTX (1.1 V)	0.18	
		PCIE_VPH (2.5 V)	0.36	

4.1.9 HDMI Power Consumption

Table 14 provides HDMI PHY currents for both Active 3D Tx with LFSR15 data and power-down modes.

Table 14. HDMI PHY Current Drain

Mode	Test Conditions	Supply	Max Current	Unit
Active	Bit rate 251.75 Mbps	HDMI_VPH	14	mA
		HDMI_VP	4.1	mA
	Bit rate 279.27 Mbps	HDMI_VPH	14	mA
		HDMI_VP	4.2	mA
	Bit rate 742.5 Mbps	HDMI_VPH	17	mA
		HDMI_VP	7.5	mA
	Bit rate 1.485 Gbps	HDMI_VPH	17	mA
		HDMI_VP	12	mA
	Bit rate 2.275 Gbps	HDMI_VPH	16	mA
		HDMI_VP	17	mA
	Bit rate 2.97 Gbps	HDMI_VPH	19	mA
		HDMI_VP	22	mA
Power-down	—	HDMI_VPH	49	µA
		HDMI_VP	1100	µA

4.2 Power Supplies Requirements and Restrictions

The system design must comply with power-up sequence, power-down sequence, and steady state guidelines as described in this section to guarantee the reliable operation of the device. Any deviation from these sequences may result in the following situations:

- Excessive current during power-up phase
- Prevention of the device from booting
- Irreversible damage to the processor (worst-case scenario)

[1] t is the maximum EIM logic (ACLK_EXSC) cycle time. The maximum allowed axi_clk frequency depends on the fixed/non-fixed latency configuration, whereas the maximum allowed EIM_BCLK frequency is:

—Fixed latency for both read and write is 104 MHz.

—Variable latency for read only is 104 MHz.

—Variable latency for write only is 52 MHz.

In variable latency configuration for write, if BCD = 0 & WBCDD = 1 or BCD = 1, axi_clk must be 104 MHz.Write BCD = 1 and 104 MHz ACLK_EXSC, will result in a EIM_BCLK of 52 MHz. When the clock branch to EIM is decreased to 104 MHz, other buses are impacted which are clocked from this source. See the CCM chapter of the *i.MX 6Solo/6DualLite Reference Manual (IMX6SDLRM)* for a detailed clock tree description.

[2] EIM_BCLK parameters are being measured from the 50% point, that is, high is defined as 50% of signal value and low is defined as 50% as signal value.

[3] For signal measurements, “High” is defined as 80% of signal value and “Low” is defined as 20% of signal value.

Figure 15 to Figure 18 provide few examples of basic EIM accesses to external memory devices with the timing parameters mentioned previously for specific control parameters settings.

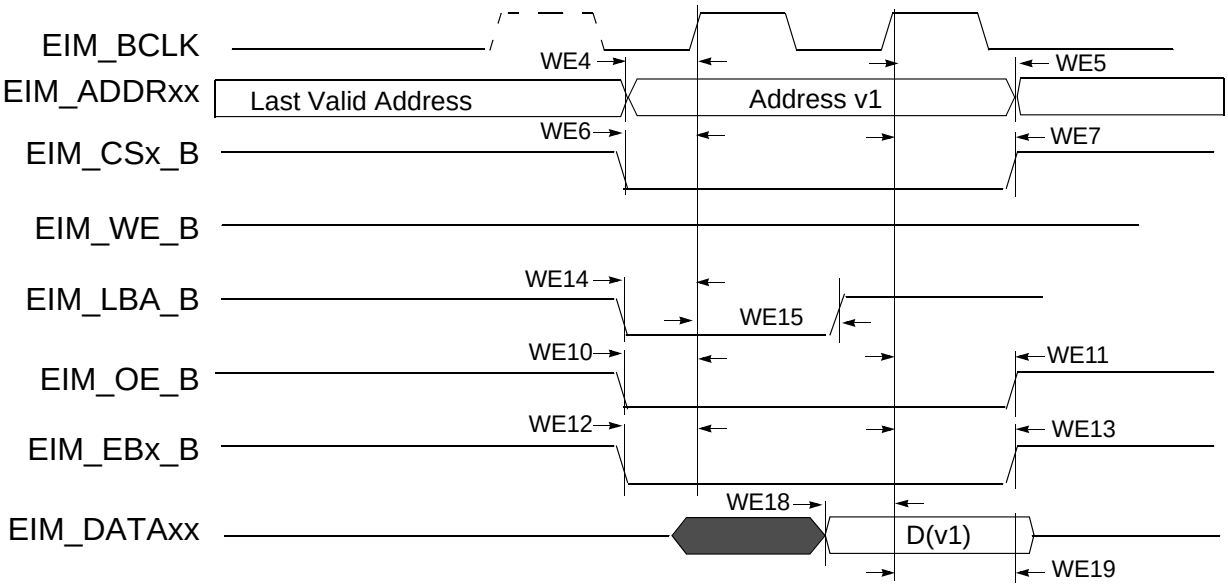
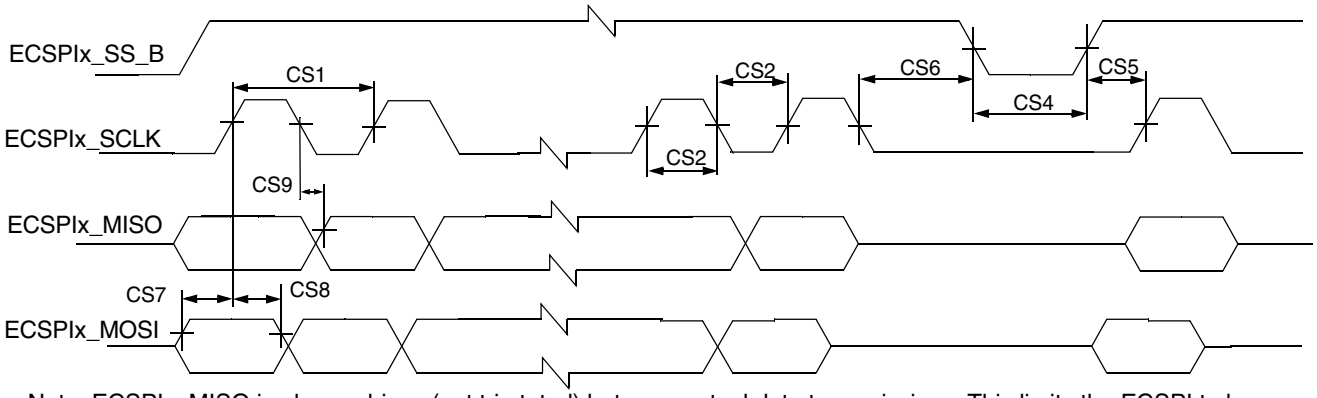


Figure 15. Synchronous Memory Read Access, WSC=1

4.11.2.2 ECSPI Slave Mode Timing

Figure 37 depicts the timing of ECSPI in slave mode. Table 50 lists the ECSPI slave mode timing characteristics.



Note: ECSPIx_MISO is always driven (not tri-stated) between actual data transmissions. This limits the ECSPI to be connected between a single master and a single slave.

Figure 37. ECSPI Slave Mode Timing Diagram

Table 50. ECSPI Slave Mode Timing Parameters

ID	Parameter	Symbol	Min	Max	Unit
CS1	ECSPIx_SCLK Cycle Time–Read ECSPIx_SCLK Cycle Time–Write	t_{clk}	43 15	—	ns
CS2	ECSPIx_SCLK High or Low Time–Read ECSPIx_SCLK High or Low Time–Write	t_{SW}	21.5 7	—	ns
CS4	ECSPIx_SS_B pulse width	t_{CSLH}	Half ECSPIx_SCLK period	—	ns
CS5	ECSPIx_SS_B Lead Time (CS setup time)	t_{SCS}	5	—	ns
CS6	ECSPIx_SS_B Lag Time (CS hold time)	t_{HCS}	5	—	ns
CS7	ECSPIx_MOSI Setup Time	t_{Smosi}	4	—	ns
CS8	ECSPIx_MOSI Hold Time	t_{Hmosi}	4	—	ns
CS9	ECSPIx_MISO Propagation Delay (C_{LOAD} = 20 pF) •	t_{PDmiso}	4	19	ns

4.11.4 Ultra High Speed SD/SDIO/MMC Host Interface (uSDHC) AC Timing

This section describes the electrical information of the uSDHC, which includes SD/eMMC4.3 (Single Data Rate) timing, eMMC4.4/4.41 (Dual Date Rate) timing and SDR104/50(SD3.0) timing.

4.11.4.1 SD/eMMC4.3 (Single Data Rate) AC Timing

Figure 40 depicts the timing of SD/eMMC4.3, and Table 52 lists the SD/eMMC4.3 timing characteristics.

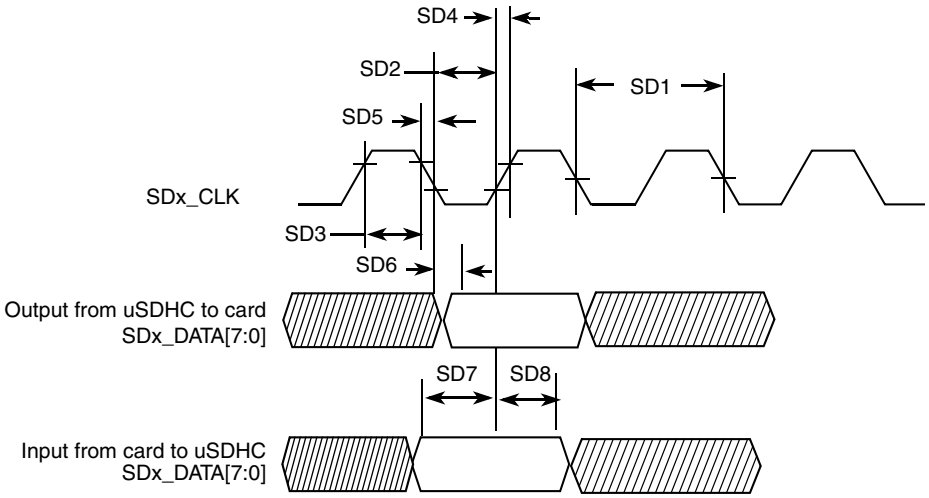


Figure 40. SD/eMMC4.3 Timing

Table 52. SD/eMMC4.3 Interface Timing Specification

ID	Parameter	Symbols	Min	Max	Unit
Card Input Clock					
SD1	Clock Frequency (Low Speed)	f_{PP}[1]	0	400	kHz
	Clock Frequency (SD/SDIO Full Speed/High Speed)	f_{PP}[2]	0	25/50	MHz
	Clock Frequency (MMC Full Speed/High Speed)	f_{PP}[3]	0	20/52	MHz
	Clock Frequency (Identification Mode)	f_{OD}	100	400	kHz
SD2	Clock Low Time	t_{WL}	7	—	ns
SD3	Clock High Time	t_{WH}	7	—	ns
SD4	Clock Rise Time	t_{TLH}	—	3	ns
SD5	Clock Fall Time	t_{THL}	—	3	ns
uSDHC Output/Card Inputs SDx_CMD, SDx_DATAx (Reference to CLK)					
SD6	uSDHC Output Delay	t_{OD}	-6.6	3.6	ns

4.11.4.4 Bus Operation Condition for 3.3 V and 1.8 V Signaling

Signaling level of SD/eMMC4.3 and eMMC4.4/4.41 modes is 3.3 V. Signaling level of SDR104/SDR50 mode is 1.8 V. The DC parameters for the NVCC_SD1, NVCC_SD2 and NVCC_SD3 supplies are identical to those shown in Table 23, "GPIO DC Parameters," on page 41.

4.11.5 Ethernet Controller (ENET) AC Electrical Specifications

The following timing specs are defined at the chip I/O pin and must be translated appropriately to arrive at timing specs/constraints for the physical interface.

4.11.5.1 ENET MII Mode Timing

This subsection describes MII receive, transmit, asynchronous inputs, and serial management signal timings.

4.11.5.1.1 MII Receive Signal Timing (ENET_RX_DATA3,2,1,0, ENET_RX_EN, ENET_RX_ER, and ENET_RX_CLK)

The receiver functions correctly up to an ENET_RX_CLK maximum frequency of 25 MHz + 1%. There is no minimum frequency requirement. Additionally, the processor clock frequency must exceed twice the ENET_RX_CLK frequency.

Figure 43 shows MII receive signal timings. Table 55 describes the timing parameters (M1–M4) shown in the figure.

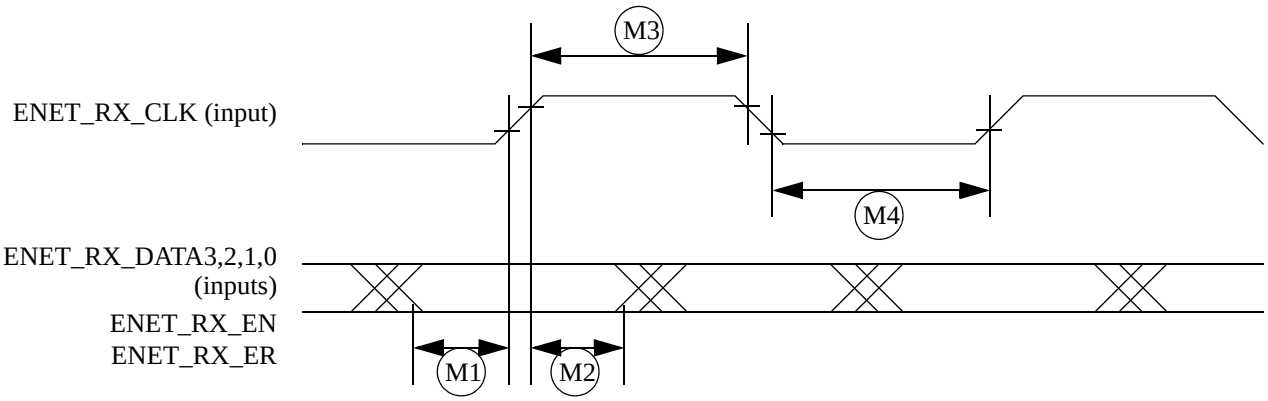


Figure 43. MII Receive Signal Timing Diagram

Table 55. MII Receive Signal Timing

ID	Characteristic[1]	Min	Max	Unit
M1	ENET_RX_DATA3,2,1,0, ENET_RX_EN, ENET_RX_ER to ENET_RX_CLK setup	5	—	ns
M2	ENET_RX_CLK to ENET_RX_DATA3,2,1,0, ENET_RX_EN, ENET_RX_ER hold	5	—	ns
M3	ENET_RX_CLK pulse width high	35%	65%	ENET_RX_CLK period
M4	ENET_RX_CLK pulse width low	35%	65%	ENET_RX_CLK period

[1] ENET_RX_EN, ENET_RX_CLK, and ENET0_RXD0 have the same timing in 10 Mbps 7-wire interface mode.

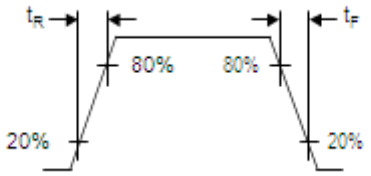


Figure 58. TMDS Output Signals Rise and Fall Time Definition

Table 62. Switching Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
TMDS Drivers Specifications						
—	Maximum serial data rate	—	—	—	3.4	Gbps
$F_{TMDSCLK}$	TMDSCLK frequency	On TMDSCLKP/N outputs	25	—	340	MHz
$P_{TMDSCLK}$	TMDSCLK period	RL = 50 Ω See Figure 54.	2.94	—	40	ns
t_{CDC}	TMDSCLK duty cycle	$t_{CDC} = t_{CPH} / P_{TMDSCLK}$ RL = 50 Ω See Figure 54.	40	50	60	%
t_{CPH}	TMDSCLK high time	RL = 50 Ω See Figure 54.	4	5	6	UI[1]
t_{CPL}	TMDSCLK low time	RL = 50 Ω See Figure 54.	4	5	6	UI[1]
—	TMDSCLK jitter[2]	RL = 50 Ω	—	—	0.25	UI[1]
$t_{SK(p)}$	Intra-pair (pulse) skew	RL = 50 Ω See Figure 56.	—	—	0.15	UI[1]
$t_{SK(pp)}$	Inter-pair skew	RL = 50 Ω See Figure 57.	—	—	1	UI[1]
t_R	Differential output signal rise time	20–80% RL = 50 Ω See Figure 58.	75	—	0.4 UI	ps
t_F	Differential output signal fall time	20–80% RL = 50 Ω See Figure 58.	75	—	0.4 UI	ps
—	Differential signal overshoot	Referred to 2x V_{SWING}	—	—	15	%
—	Differential signal undershoot	Referred to 2x V_{SWING}	—	—	25	%

1 UI means TMDS clock unit.

2 Relative to ideal recovery clock, as specified in the HDMI specification, version 1.4a, section 4.2.3.

Table 64. Camera Input Signal Cross Reference, Format, and Bits Per Cycle (continued)

Signal Name[1]	RGB565 8 bits 2 cycles	RGB565[2] 8 bits 3 cycles	RGB666[3] 8 bits 3 cycles	RGB888 8 bits 3 cycles	YCbCr[4] 8 bits 2 cycles	RGB565[5] 16 bits 1 cycle	YCbCr[6] 16 bits 1 cycle	YCbCr[7] 16 bits 1 cycle	YCbCr[8] 20 bits 1 cycle
IPUx_CSIx_ DATA13	B[1], G[4]	R[3],G[5],B[3]	R/G/B[5]	R/G/B[1]	Y/C[1]	G[4]	Y[1]	Y[1]	Y[3]
IPUx_CSIx_ DATA14	B[2], G[5]	R[4],G[0],B[4]	R/G/B[0]	R/G/B[2]	Y/C[2]	G[5]	Y[2]	Y[2]	Y[4]
IPUx_CSIx_ DATA15	B[3], R[0]	R[0],G[1],B[0]	R/G/B[1]	R/G/B[3]	Y/C[3]	R[0]	Y[3]	Y[3]	Y[5]
IPUx_CSIx_ DATA16	B[4], R[1]	R[1],G[2],B[1]	R/G/B[2]	R/G/B[4]	Y/C[4]	R[1]	Y[4]	Y[4]	Y[6]
IPUx_CSIx_ DATA17	G[0], R[2]	R[2],G[3],B[2]	R/G/B[3]	R/G/B[5]	Y/C[5]	R[2]	Y[5]	Y[5]	Y[7]
IPUx_CSIx_ DATA18	G[1], R[3]	R[3],G[4],B[3]	R/G/B[4]	R/G/B[6]	Y/C[6]	R[3]	Y[6]	Y[6]	Y[8]
IPUx_CSIx_ DATA19	G[2], R[4]	R[4],G[5],B[4]	R/G/B[5]	R/G/B[7]	Y/C[7]	R[4]	Y[7]	Y[7]	Y[9]

1 IPUx_CSIx stands for IPUx_CSI0 or IPUx_CSI1.

2 The MSB bits are duplicated on LSB bits implementing color extension.

3 The two MSB bits are duplicated on LSB bits implementing color extension.

4 YCbCr, 8 bits—Supported within the BT.656 protocol (sync embedded within the data stream).

5 RGB 16 bits—Supported in two ways: (1) As a “generic data” input, with no on-the-fly processing; (2) With on-the-fly processing, but only under some restrictions on the control protocol.

6 YCbCr 16 bits—Supported as a “generic-data” input, with no on-the-fly processing.

7 YCbCr 16 bits—Supported as a sub-case of the YCbCr, 20 bits, under the same conditions (BT.1120 protocol).

8 YCbCr, 20 bits—Supported only within the BT.1120 protocol (syncs embedded within the data stream).

4.11.10.2 Sensor Interface Timings

There are three camera timing modes supported by the IPU.

4.11.10.2.1 BT.656 and BT.1120 Video Mode

Smart camera sensors, which include imaging processing, usually support video mode transfer. They use an embedded timing syntax to replace the IPUx_CSIx_VSYNC and IPUx_CSIx_HSYNC signals. The timing syntax is defined by the BT.656/BT.1120 standards.

This operation mode follows the recommendations of ITU BT.656/ ITU BT.1120 specifications. The only control signal used is IPUx_CSIx_PIX_CLK. Start-of-frame and active-line signals are embedded in the data stream. An active line starts with a SAV code and ends with a EAV code. In some cases, digital blanking is inserted in between EAV and SAV code. The CSI decodes and filters out the timing-coding from the data stream, thus recovering IPUx_CSIx_VSYNC and IPUx_CSIx_HSYNC signals for internal use. On BT.656 one component per cycle is received over the IPUx_CSIx_DATA_EN bus. On BT.1120 two components per cycle are received over the IPUx_CSIx_DATA_EN bus.

The display access can be whole number of DI clock (Tdiclk) only. The IPP_DATA can not be moved relative to the local start point. The data bus of the synchronous interface is output direction only.

4.11.10.6.2 LCD Interface Functional Description

Figure 63 depicts the LCD interface timing for a generic active matrix color TFT panel. In this figure, signals are shown with negative polarity. The sequence of events for active matrix interface timing is:

- DI_CLK internal DI clock is used for calculation of other controls.
- IPP_DISP_CLK latches data into the panel on its negative edge (when positive polarity is selected). In active mode, IPP_DISP_CLK runs continuously.
- HSYNC causes the panel to start a new line. (Usually IPUx_DIx_PIN02 is used as HSYNC.)
- VSYNC causes the panel to start a new frame. It always encompasses at least one HSYNC pulse. (Usually IPUx_DIx_PIN03 is used as VSYNC.)
- DRDY acts like an output enable signal to the CRT display. This output enables the data to be shifted onto the display. When disabled, the data is invalid and the trace is off.
  (DRDY can be used either synchronous or asynchronous generic purpose pin as well.)

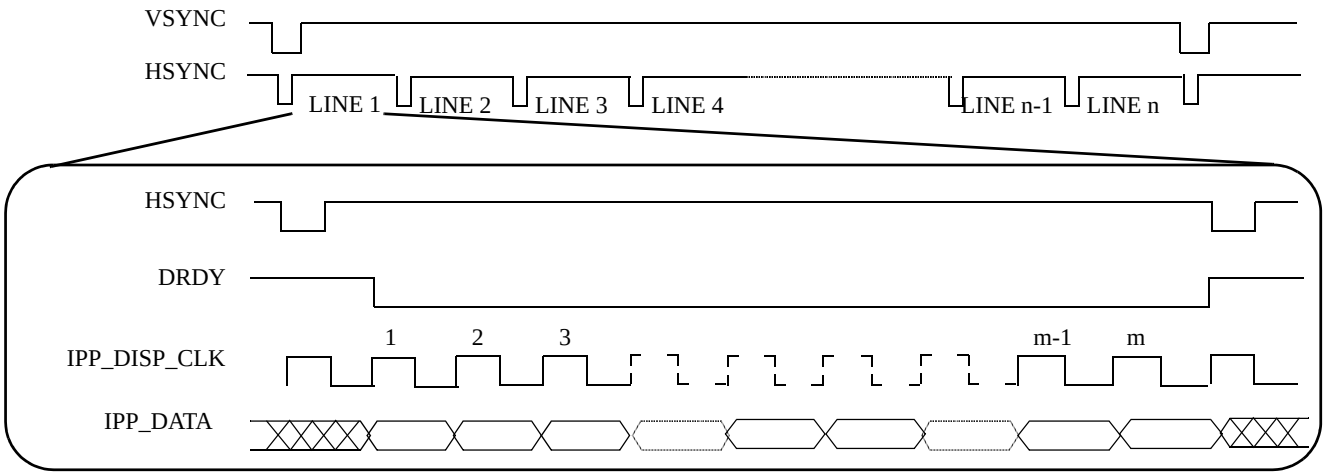


Figure 63. Interface Timing Diagram for TFT (Active Matrix) Panels

4.11.10.6.3 TFT Panel Sync Pulse Timing Diagrams

Figure 64 depicts the horizontal timing (timing of one line), including both the horizontal sync pulse and the data. All the parameters shown in the figure are programmable. All controls are started by

4.11.11 LVDS Display Bridge (LDB) Module Parameters

The LVDS interface complies with TIA/EIA 644-A standard. For more details, see TIA/EIA STANDARD 644-A, "*Electrical Characteristics of Low Voltage Differential Signaling (LVDS) Interface Circuits*".

Table 69. LVDS Display Bridge (LDB) Electrical Specification

Parameter	Symbol	Test Condition	Min	Max	Units
Differential Voltage Output Voltage	V_{OD}	100 Ω Differential load	250	450	mV
Output Voltage High	Voh	100 Ω differential load (0 V Diff—Output High Voltage static)	1.25	1.6	V
Output Voltage Low	Vol	100 Ω differential load (0 V Diff—Output Low Voltage static)	0.9	1.25	V
Offset Static Voltage	V_{OS}	Two 49.9 Ω resistors in series between N-P terminal, with output in either Zero or One state, the voltage measured between the 2 resistors.	1.15	1.375	V
VOS Differential	V_{OSDIFF}	Difference in V_{OS} between a One and a Zero state	-50	50	mV
Output short circuited to GND	ISA ISB	With the output common shorted to GND	-24	24	mA
VT Full Load Test	VTLoad	100 Ω Differential load with a 3.74 kΩ load between GND and IO Supply Voltage	247	454	mV

4.11.12 MIPI D-PHY Timing Parameters

This section describes MIPI D-PHY electrical specifications, compliant with MIPI CSI-2 version 1.0, D-PHY specification Rev. 1.0 (for MIPI sensor port x2 lanes) and MIPI DSI Version 1.01, and D-PHY specification Rev. 1.0 (and also DPI version 2.0, DBI version 2.0, DSC version 1.0a at protocol layer) (for MIPI display port x2 lanes).

4.11.12.1 Electrical and Timing Information

Table 70. Electrical and Timing Information

Symbol	Parameters	Test Conditions	Min	Typ	Max	Unit
Input DC Specifications - Apply to DSI_CLK_P/DSI_CLK_N and DSI_DATA_P/DSI_DATA_N inputs						
V_I	Input signal voltage range	Transient voltage range is limited from -300 mV to 1600 mV	-50	—	1350	mV
V_{LEAK}	Input leakage current	VGNDSH(min) = VI = VGNDSH(max) + VOH(absmax) Lane module in LP Receive Mode	-10	—	10	mA
V_{GNDSH}	Ground Shift	—	-50	—	50	mV
$V_{OH(absmax)}$	Maximum transient output voltage level	—	—	—	1.45	V

4.11.13.2 Pipelined Data Flow

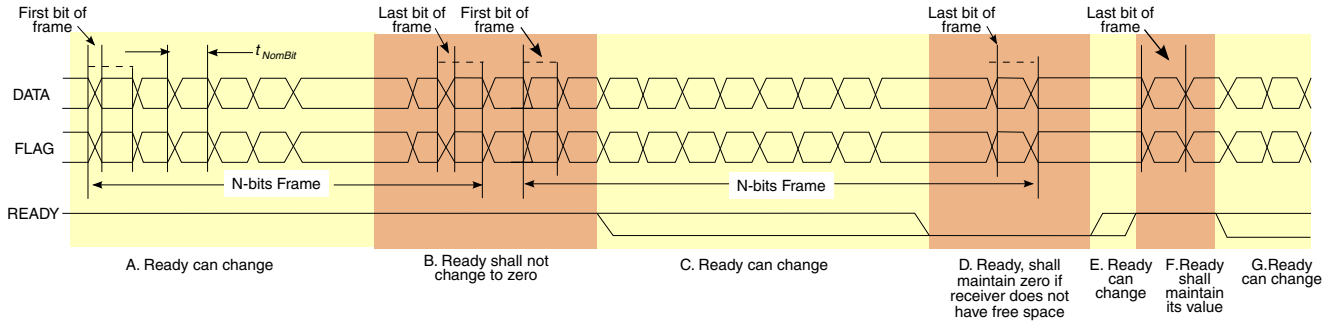


Figure 75. Pipelined Data Flow Ready Signal Timing (Frame Transmission Mode)

4.11.13.3 Receiver Real-Time Data Flow

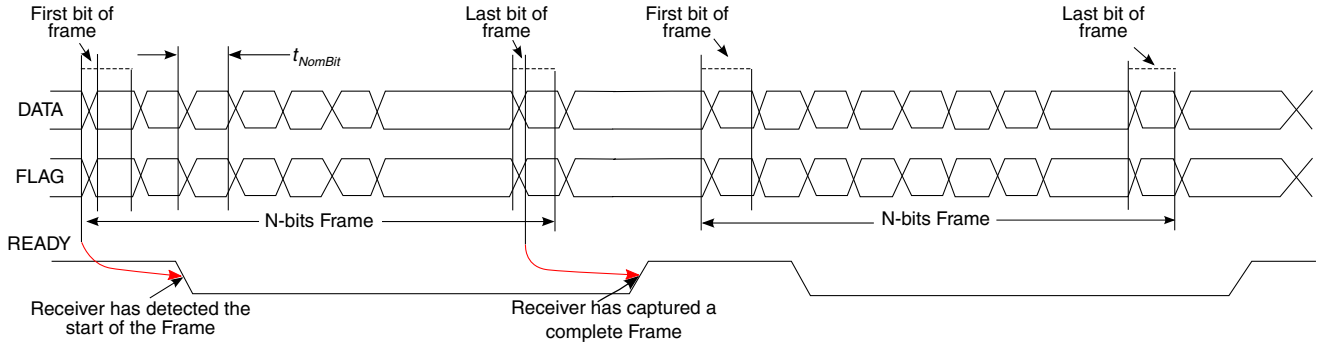


Figure 76. Receiver Real-Time Data Flow READY Signal Timing

4.11.13.4 Synchronized Data Flow Transmission with Wake

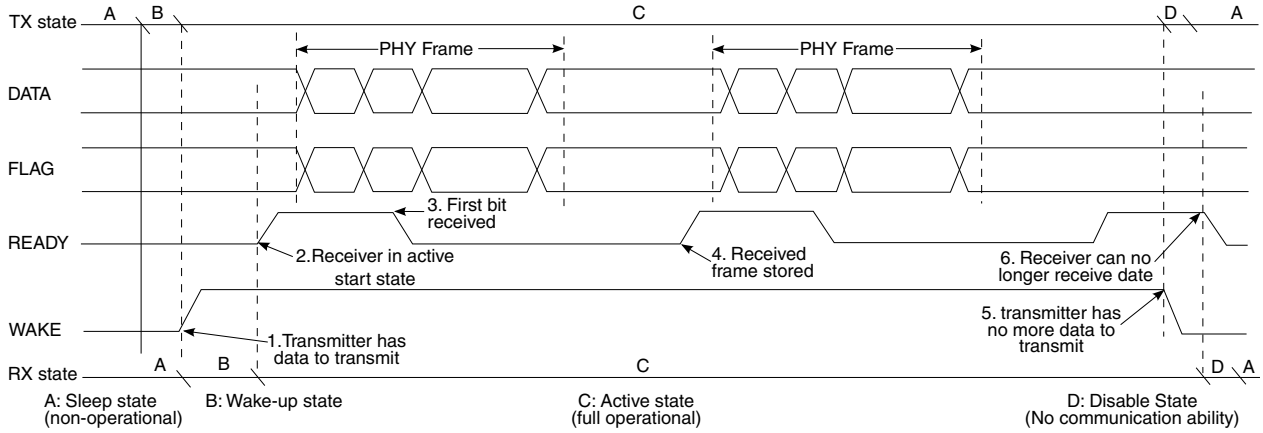


Figure 77. Synchronized Data Flow Transmission with WAKE

4.11.13.5 Stream Transmission Mode Frame Transfer

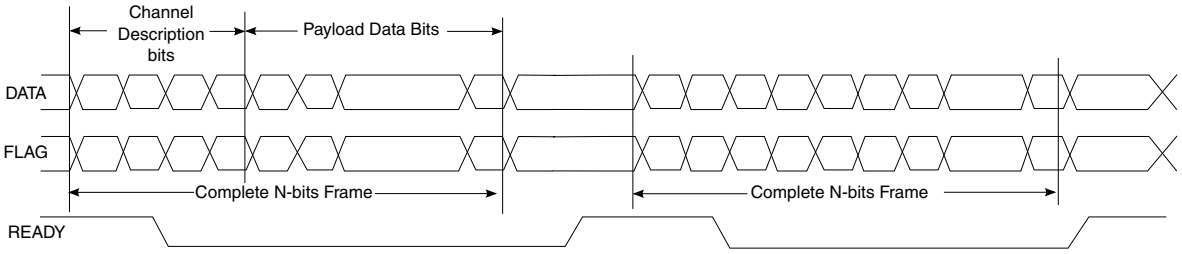


Figure 78. Stream Transmission Mode Frame Transfer (Synchronized Data Flow)

4.11.13.6 Frame Transmission Mode (Synchronized Data Flow)

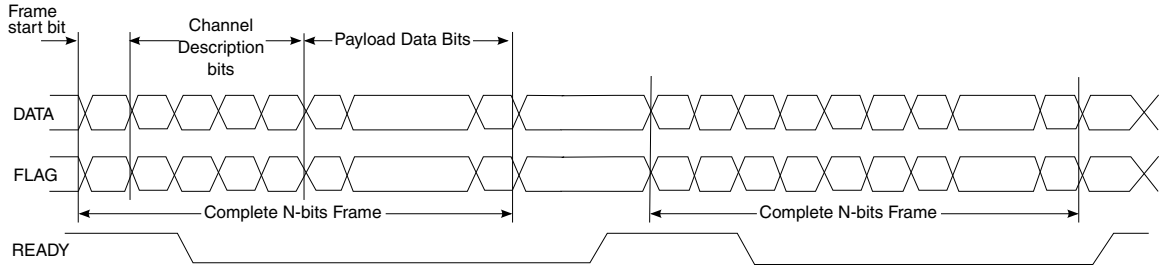


Figure 79. Frame Transmission Mode Transfer of Two Frames (Synchronized Data Flow)

4.11.13.7 Frame Transmission Mode (Pipelined Data Flow)

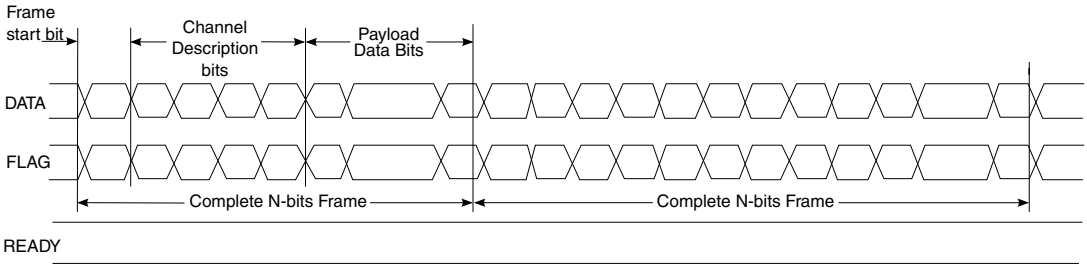


Figure 80. Frame Transmission Mode Transfer of Two Frames (Pipelined Data Flow)

4.11.13.8 DATA and FLAG Signal Timing Requirement for a 15 pF Load

Table 72. DATA and FLAG Timing

Parameter	Description	1 Mbit/s	100 Mbit/s	200 Mbit/s
$t_{Bit, nom}$	Nominal bit time	1000 ns	10.0 ns	5.00 ns
$t_{Rise, min}$ and $t_{Fall, min}$	Minimum allowed rise and fall time	2.00 ns	2.00 ns	1.00 ns
$t_{TxToRxSkew, maxfq}$	Maximum skew between transmitter and receiver package pins	50.0 ns	0.5.0 ns	0.25 ns

4.11.19 SSI Timing Parameters

This section describes the timing parameters of the SSI module. The connectivity of the serial synchronous interfaces are summarized in Table 81.

Table 81. AUDMUX Port Allocation

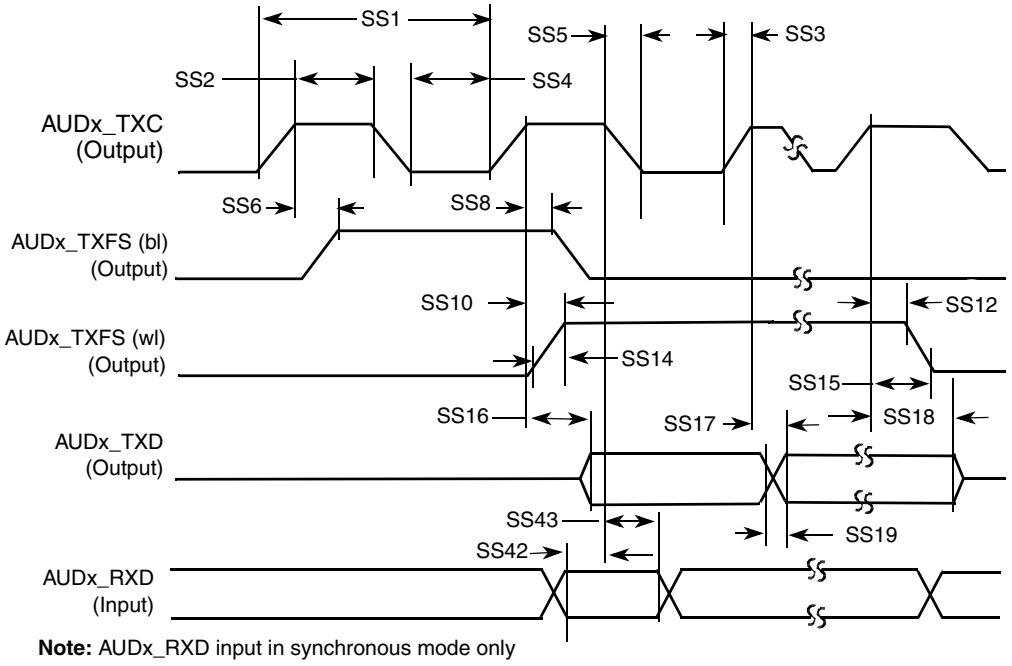
Port	Signal Nomenclature	Type and Access
AUDMUX port 1	SSI 1	Internal
AUDMUX port 2	SSI 2	Internal
AUDMUX port 3	AUD3	External—AUD3 I/O
AUDMUX port 4	AUD4	External—EIM or CSPI1 I/O through IOMUXC
AUDMUX port 5	AUD5	External—EIM or SD1 I/O through IOMUXC
AUDMUX port 6	AUD6	External—EIM or DISP2 through IOMUXC
AUDMUX port 7	SSI 3	Internal

NOTE

The terms WL and BL used in the timing diagrams and tables refer to Word Length (WL) and Bit Length (BL).

4.11.19.1 SSI Transmitter Timing with Internal Clock

Figure 91 depicts the SSI transmitter internal clock timing and Table 82 lists the timing parameters for the SSI transmitter internal clock.



Note: AUDx_RXD input in synchronous mode only

Figure 91. SSI Transmitter Internal Clock Timing Diagram

Table 84. SSI Transmitter Timing with External Clock (continued)

ID	Parameter	Min	Max	Unit
Synchronous External Clock Operation				
SS44	AUDx_RXD setup before AUDx_TXC falling	10.0	—	ns
SS45	AUDx_RXD hold after AUDx_TXC falling	2.0	—	ns
SS46	AUDx_RXD rise/fall time	—	6.0	ns

NOTE

- All the timings for the SSI are given for a non-inverted serial clock polarity (TSCKP/RSCKP = 0) and a non-inverted frame sync (TFSI/RFSI = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the clock signal AUDx_TXC/AUDx_RXC and/or the frame sync AUDx_TXFS/AUDx_RXFS shown in the tables and in the figures.
- All timings are on Audiomux Pads when SSI is being used for data transfer.
- The terms WL and BL refer to Word Length (WL) and Bit Length (BL).
- For internal Frame Sync operation using external clock, the frame sync timing is same as that of transmit data (for example, during AC97 mode of operation).

4.11.19.4 SSI Receiver Timing with External Clock

Figure 94 depicts the SSI receiver external clock timing and Table 85 lists the timing parameters for the receiver timing with the external clock.

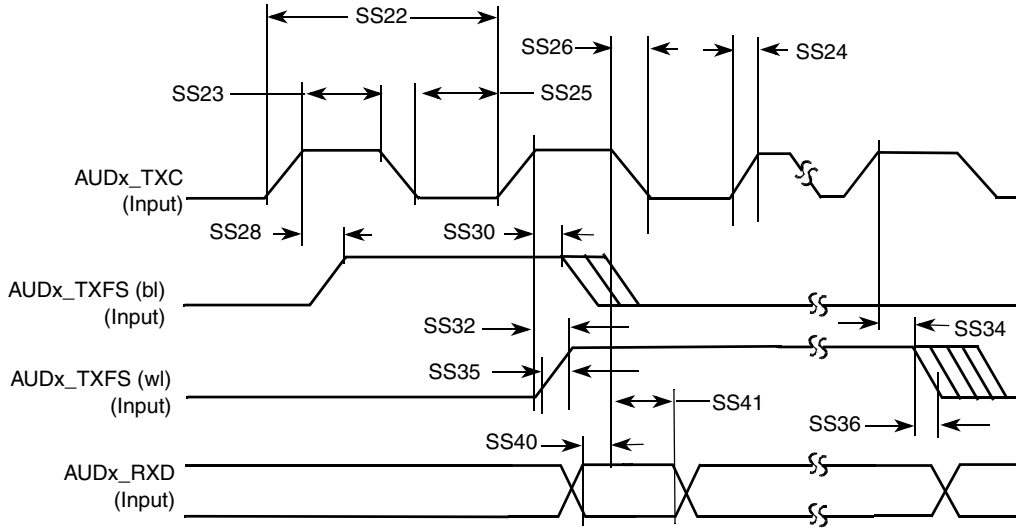


Figure 94. SSI Receiver External Clock Timing Diagram

Table 85. SSI Receiver Timing with External Clock

ID	Parameter	Min	Max	Unit
External Clock Operation				
SS22	AUDx_TXC/AUDx_RXC clock period	81.4	—	ns
SS23	AUDx_TXC/AUDx_RXC clock high period	36	—	ns
SS24	AUDx_TXC/AUDx_RXC clock rise time	—	6.0	ns
SS25	AUDx_TXC/AUDx_RXC clock low period	36	—	ns
SS26	AUDx_TXC/AUDx_RXC clock fall time	—	6.0	ns
SS28	AUDx_RXC high to AUDx_TXFS (bl) high	-10	15.0	ns
SS30	AUDx_RXC high to AUDx_TXFS (bl) low	10	—	ns
SS32	AUDx_RXC high to AUDx_TXFS (wl) high	-10	15.0	ns
SS34	AUDx_RXC high to AUDx_TXFS (wl) low	10	—	ns
SS35	AUDx_TXC/AUDx_RXC External AUDx_TXFS rise time	—	6.0	ns
SS36	AUDx_TXC/AUDx_RXC External AUDx_TXFS fall time	—	6.0	ns
SS40	AUDx_RXD setup time before AUDx_RXC low	10	—	ns
SS41	AUDx_RXD hold time after AUDx_RXC low	2	—	ns

NOTE

- All the timings for the SSI are given for a non-inverted serial clock polarity (TSCKP/RSCKP = 0) and a non-inverted frame sync (TFSI/RFSI = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the clock signal AUDx_TXC/AUDx_RXC and/or the frame sync AUDx_TXFS/AUDx_RXFS shown in the tables and in the figures.
- All timings are on Audiomux Pads when SSI is being used for data transfer.
- The terms, WL and BL, refer to Word Length (WL) and Bit Length(BL).
- For internal Frame Sync operation using external clock, the frame sync timing is same as that of transmit data (for example, during AC97 mode of operation).